

Claims

1. Paper (1, 4), in particular décor paper (1), which is provided with conduc-
5 tive substances and in particular provided with carbon.
2. Paper (1, 4) according to claim 1, which is in addition provided with an
urea resin and/or a melamine resin and/or an acrylate resin.
- 10 3. Paper (1, 4) according to claim 1 or 2, which is provided with a décor as
well as preferably abrasion-resistant particles (2) provided on the décor, in
particular preferred with aluminum oxide or corundum.
4. Paper according to any of the preceding claims, with a paper weight be-
15 tween 10 g/m² and 50 g/m².
5. Paper according to any of the preceding claims, which is provided with
carbon with an average particle size of less than 1,000 nm, preferably less
than 500 nm, as well as preferably less than 1 nm.
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6. Paper according to any of the preceding claims, wherein the paper contains
acrylate in its interior.
7. Panel for flooring, in particular comprising a décor paper (1) according to
25 one of the preceding claims, with a surface which is provided with a décor
and which contains conductive particles and preferably carbon particles.
8. Panel according to any of the preceding claims, wherein the surface is
formed of a décor paper (1) with abrasion-resistant particles (2), in particu-

lar corundum, applied thereon, which décor paper has a higher electrical conductivity compared to other papers used during the manufacture of the panel.

- 5 9. Panel according to any of the preceding claims, wherein the surface contains a urea resin and/or a melamine resin and/or an acrylate resin.
- 10 10. Panel according to any of the preceding claims, wherein the underside is provided with a paper (5) serving as counter-acting paper, which is preferably provided with urea resin and/or acrylate resin.
11. 11. Panel according to any of the preceding claims, comprising a carrier board (3) made from HDF.
- 15 12. Panel according to any of the preceding claims, which is provided with coupling elements on its sides.